Electronic Patent Application Fee Transmittal							
Application Number:	09829587						
Filing Date:	09-	09-Apr-2001					
Title of Invention:	SY:	SYSTEM FOR, AND METHOD OF, ETCHING A SURFACE ON A WAFER					
First Named Inventor/Applicant Name:	Pa	Pavel N. Laptev					
Filer:	Sh	Sheldon R. Meyer/carole wong					
Attorney Docket Number:	TE	TEGL-01212US0					
Filed as Small Entity							
Utility under 35 USC 111(a) Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
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Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Utility Appl issue fee		2501	1	755	755		
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